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FCB070N65S3

N-Channel SuperFET® III MOSFET

650 V, 44 A, 70 mΩ

Features

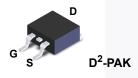
- 700 V @ T_J = 150 °C
- $R_{DS(on)} = 62 \text{ m}\Omega \text{ (Typ.)}$
- Ultra Low Gate Charge (Typ. Q_q = 78 nC)
- Low Effective Output Capacitance (Typ. C_{oss(eff.)} = 715 pF)
- 100% Avalanche Tested
- · RoHS Compliant

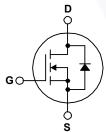
Applications

- · Telecom / Server Power Supplies
- · Industrial Power Supplies
- · UPS / Solar

Description

SuperFET[®] III MOSFET is ON Semiconductor's brand-new high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low on-resistance and lower gate charge performance. This advance technology is tailored to minimize conduction loss, provide superior switching performance, and withstand extreme dv/dt rate. Consequently, SuperFET III MOSFET is very suitable for various AC/DC power conversion for system miniaturization and higher efficiency.





Absolute Maximum Ratings T_C = 25°C unless otherwise noted.

	Parameter	FCB070N65S3	Unit
Drain to Source Voltage		650	V
Cata ta Causaa Maltaga	- DC	±30	V
Gate to Source voltage	- AC (f>1 Hz)	±30	V
Desir Coment	- Continuous (T _C = 25°C)	44	
Drain Current	- Continuous (T _C = 100°C)	28	A
Drain Current	- Pulsed (Note 1)	110	Α
Single Pulsed Avalanche Energ	y (Note 2)	214	mJ
Avalanche Current	Avalanche Current (Note 1)		Α
Repetitive Avalanche Energy	(Note 1)	3.12	mJ
MOSFET dv/dt		100	1//
Peak Diode Recovery dv/dt	(Note 3)	20	V/ns
Device Dissipation	$(T_C = 25^{\circ}C)$	312	W
Power Dissipation	- Derate Above 25°C	2.5	W/°C
Operating and Storage Tempera	Operating and Storage Temperature Range		
Maximum Lead Temperature for	Soldering, 1/8" from Case for 5 Seconds	300	οС
	Gate to Source Voltage Drain Current Drain Current Single Pulsed Avalanche Energ Avalanche Current Repetitive Avalanche Energy MOSFET dv/dt Peak Diode Recovery dv/dt Power Dissipation Operating and Storage Tempera	$ \begin{array}{c} \text{Drain to Source Voltage} \\ \text{Gate to Source Voltage} \\ \end{array} \begin{array}{c} -\text{DC} \\ -\text{AC} \\ \end{array} \begin{array}{c} -\text{Continuous} \ (T_{\text{C}} = 25^{\circ}\text{C}) \\ -\text{Continuous} \ (T_{\text{C}} = 100^{\circ}\text{C}) \\ \end{array} \\ \text{Drain Current} \\ \end{array} \begin{array}{c} -\text{Continuous} \ (T_{\text{C}} = 100^{\circ}\text{C}) \\ -\text{Continuous} \ (T_{\text{C}} = 100^{\circ}\text{C}) \\ \end{array} \\ \text{Drain Current} \\ \text{Single Pulsed Avalanche Energy} \\ \text{Avalanche Current} \\ \text{Repetitive Avalanche Energy} \\ \text{Repetitive Avalanche Energy} \\ \text{MOSFET dv/dt} \\ \text{Peak Diode Recovery dv/dt} \\ \end{array} \begin{array}{c} \text{(Note 1)} \\ \text{(Note 3)} \\ \end{array} \\ \end{array}$	

Thermal Characteristics

Symbol	Parameter	FCB070N65S3	Unit
$R_{ heta JC}$	Thermal Resistance, Junction to Case, Max.	0.4	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Minimum Pad of 2-oz Copper), Max.	62.5	°C/W
	Thermal Resistance, Junction to Ambient (1 in ² Pad of 2-oz Copper), Max.	40	

Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FCB070N65S3	FCB070N65S3	D ² -PAK	Tape and Reel	330 mm	24 mm	800 units

Electrical Characteristics $T_C = 25^{\circ}C$ unless otherwise noted.

Symbol	Parameter	lest Conditions	win.	тур.	wax.	Unit
Off Charac	cteristics					
BV _{DSS}	Drain to Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 1 \text{ mA}, T_J = 25^{\circ}\text{C}$	650	-	-	V
Diani to Source Breakdown voltage	$V_{GS} = 0 \text{ V}, I_D = 1 \text{ mA}, T_J = 150^{\circ}\text{C}$	700	-	-	V	
ΔBV _{DSS} / ΔΤ _J	Breakdown Voltage Temperature Coefficient	I _D = 1 mA, Referenced to 25°C	-	0.72	-	V/°C
1	Zero Gate Voltage Drain Current	$V_{DS} = 650 \text{ V}, V_{GS} = 0 \text{ V}$	1	-	1	μА
I _{DSS}	zero Gate voltage Drain Current	$V_{DS} = 520 \text{ V}, V_{GS} = 0 \text{ V}, T_{C} = 125^{\circ}\text{C}$	1	2.2	-	μΑ
I _{GSS}	Gate to Body Leakage Current	$V_{GS} = \pm 30 \text{ V}, V_{DS} = 0 \text{ V}$		-	±100	nA

On Characteristics

V _{GS(th)}	Gate Threshold Voltage	$V_{GS} = V_{DS}$, $I_D = 4.4$ mA	2.5	-	4.5	V
R _{DS(on)}	Static Drain to Source On Resistance	$V_{GS} = 10 \text{ V}, I_D = 22 \text{ A}$	-	62	70	mΩ
9 _{FS}	Forward Transconductance	$V_{DS} = 20 \text{ V}, I_{D} = 22 \text{ A}$	-	29	-	S

Dynamic Characteristics

C _{iss}	Input Capacitance	V _{DS} = 400 V, V _{GS} = 0 V,	- \	3090	-	pF
C _{oss}	Output Capacitance	f = 1 MHz	-	68	-	pF
C _{oss(eff.)}	Effective Output Capacitance	V _{DS} = 0 V to 400 V, V _{GS} = 0 V	-	715	-	pF
C _{oss(er.)}	Energy Related Output Capacitance	V _{DS} = 0 V to 400 V, V _{GS} = 0 V	-	104	-	pF
Q _{g(tot)}	Total Gate Charge at 10V	V _{DS} = 400 V, I _D = 22 A,	-	78	-	nC
Q_{gs}	Gate to Source Gate Charge	V _{GS} = 10 V	-	18	-	nC
Q _{gd}	Gate to Drain "Miller" Charge	(Note 4)	-	30	-	nC
ESR	Equivalent Series Resistance	f = 1 MHz	-	0.6	-	Ω

Switching Characteristics

$t_{d(on)}$	Turn-On Delay Time			-	26	-	ns
t _r	Turn-On Rise Time	$V_{DD} = 400 \text{ V}, I_D = 22 \text{ A},$		-	52	-	ns
t _{d(off)}	Turn-Off Delay Time	V_{GS} = 10 V, R_g = 4.7 Ω		- /	89	-	ns
t _f	Turn-Off Fall Time		(Note 4)		16	-	ns

Drain-Source Diode Characteristics

Is	Maximum Continuous Source to Drain Diode Forward Current		-	-	44	Α
I _{SM}	Maximum Pulsed Source to Drain Diode Forward Current		-	-	110	Α
V_{SD}	Source to Drain Diode Forward Voltage	V _{GS} = 0 V, I _{SD} = 22 A	-	-	1.2	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0 V, I _{SD} = 22 A,	-	435	-	ns
Q _{rr}	Reverse Recovery Charge	$dI_F/dt = 100 A/\mu s$	-	9.2	-//	μС

Notes

- 1. Repetitive rating: pulse width limited by maximum junction temperature.
- 2. I_{AS} = 4.8 A, R_G = 25 Ω , starting T_J = 25°C.
- 3. I $_{SD} \leq$ 44 A, di/dt \leq 200 A/µs, V $_{DD} \leq$ BV $_{DSS},$ starting T $_{J}$ = 25°C.
- ${\bf 4.} \ {\bf Essentially\ independent\ of\ operating\ temperature\ typical\ characteristic.}$

Typical Performance Characteristics

Figure 1. On-Region Characteristics

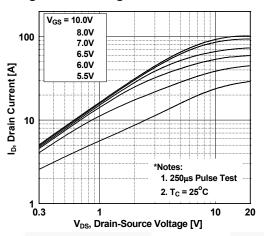


Figure 3. On-Resistance Variation vs.

Drain Current and Gate Voltage

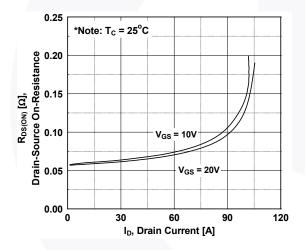


Figure 5. Capacitance Characteristics

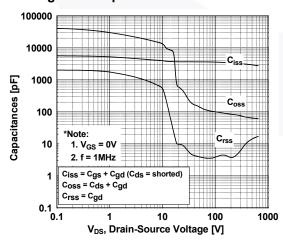


Figure 2. Transfer Characteristics

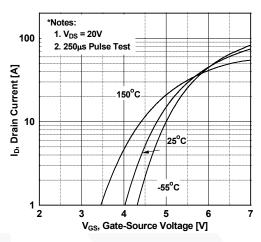


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

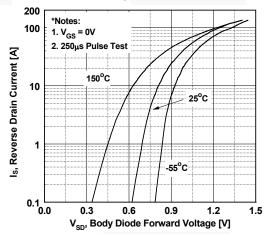
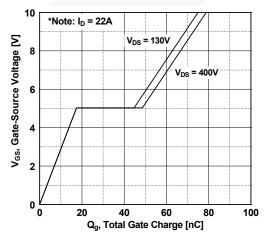


Figure 6. Gate Charge Characteristics



Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

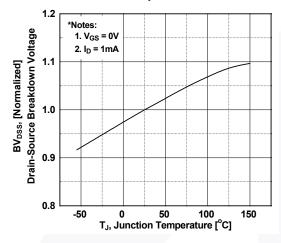


Figure 9. Maximum Safe Operating Area

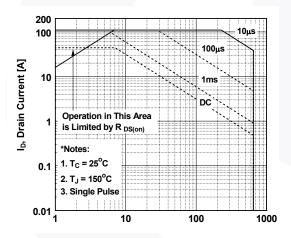


Figure 11. Eoss vs. Drain to Source Voltage

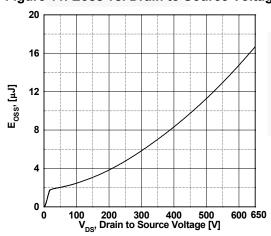


Figure 8. On-Resistance Variation vs. Temperature

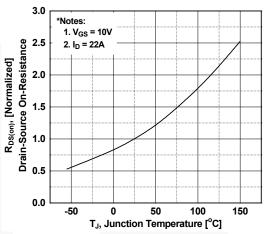
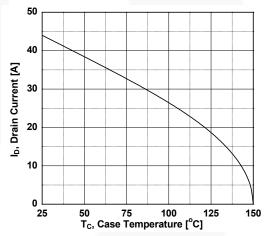
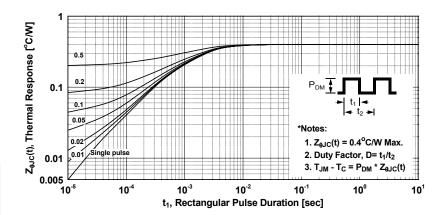


Figure 10. Maximum Drain Current vs. Case Temperature



Typical Performance Characteristics (Continued)

Figure 12. Transient Thermal Response Curve



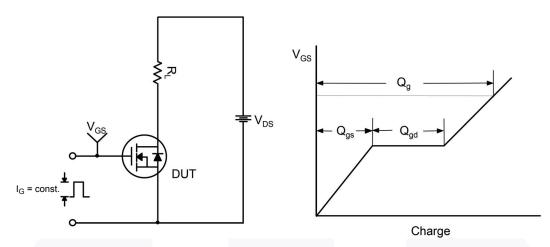


Figure 13. Gate Charge Test Circuit & Waveform

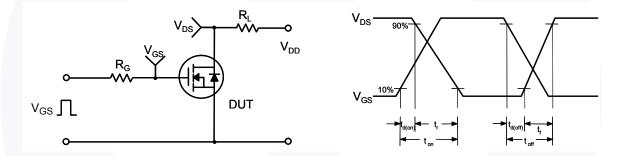


Figure 14. Resistive Switching Test Circuit & Waveforms

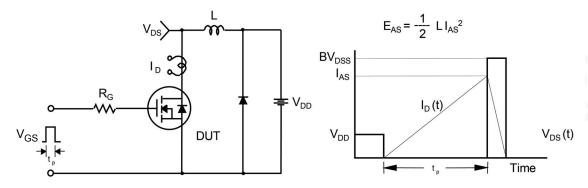


Figure 15. Unclamped Inductive Switching Test Circuit & Waveforms

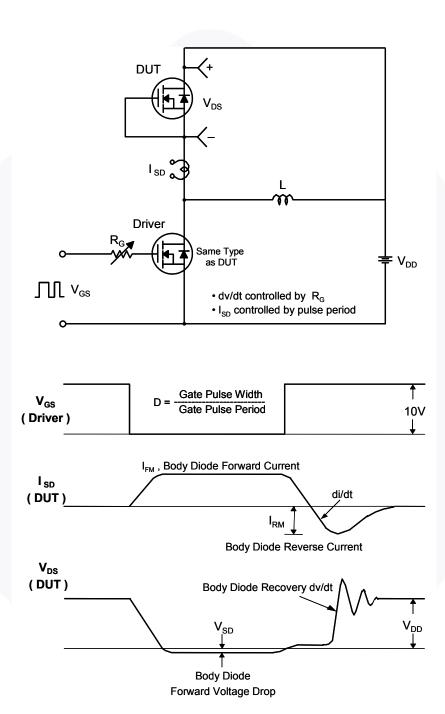
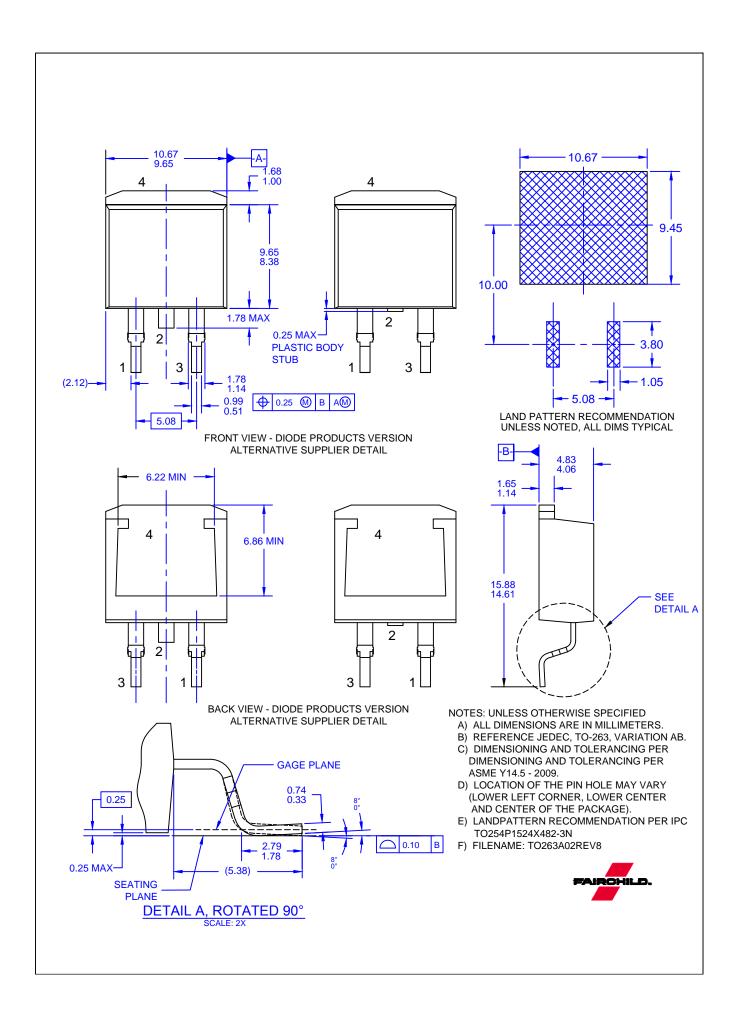


Figure 16. Peak Diode Recovery dv/dt Test Circuit & Waveforms



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